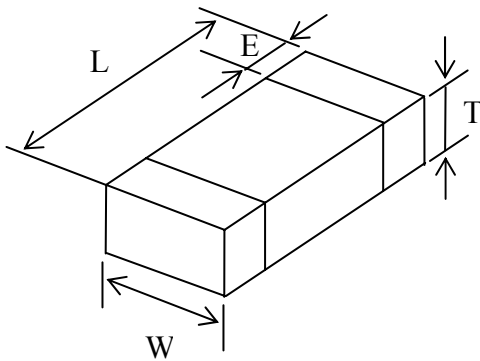


Multilayer chip bead 1005 (0402) series

PRODUCT DETAIL

Electrical Characteristics			Test Instruments
Z	Ω (Ref. Page 2)	TEST FREQ: (Ref. Page 2) MHz TEST LEVEL: 100 mV	<ul style="list-style-type: none"> •HP4291B RF IMPEDANCE / MATERIAL ANALYZER •HP4338A/B MILLIOHMMETER •ABM 8306D DC POWER SUPPLY
θ	NA		
SRF	NA		
DCR	Ω (Ref. Page 2)		
IDC	mA (Ref. Page 2)		

SHAPES AND DIMENSIONS



Unit: mm

TYPE	1005
L	1.0±0.10
W	0.5±0.10
T	0.5±0.10
E	0.25±0.1

Specification For Approval

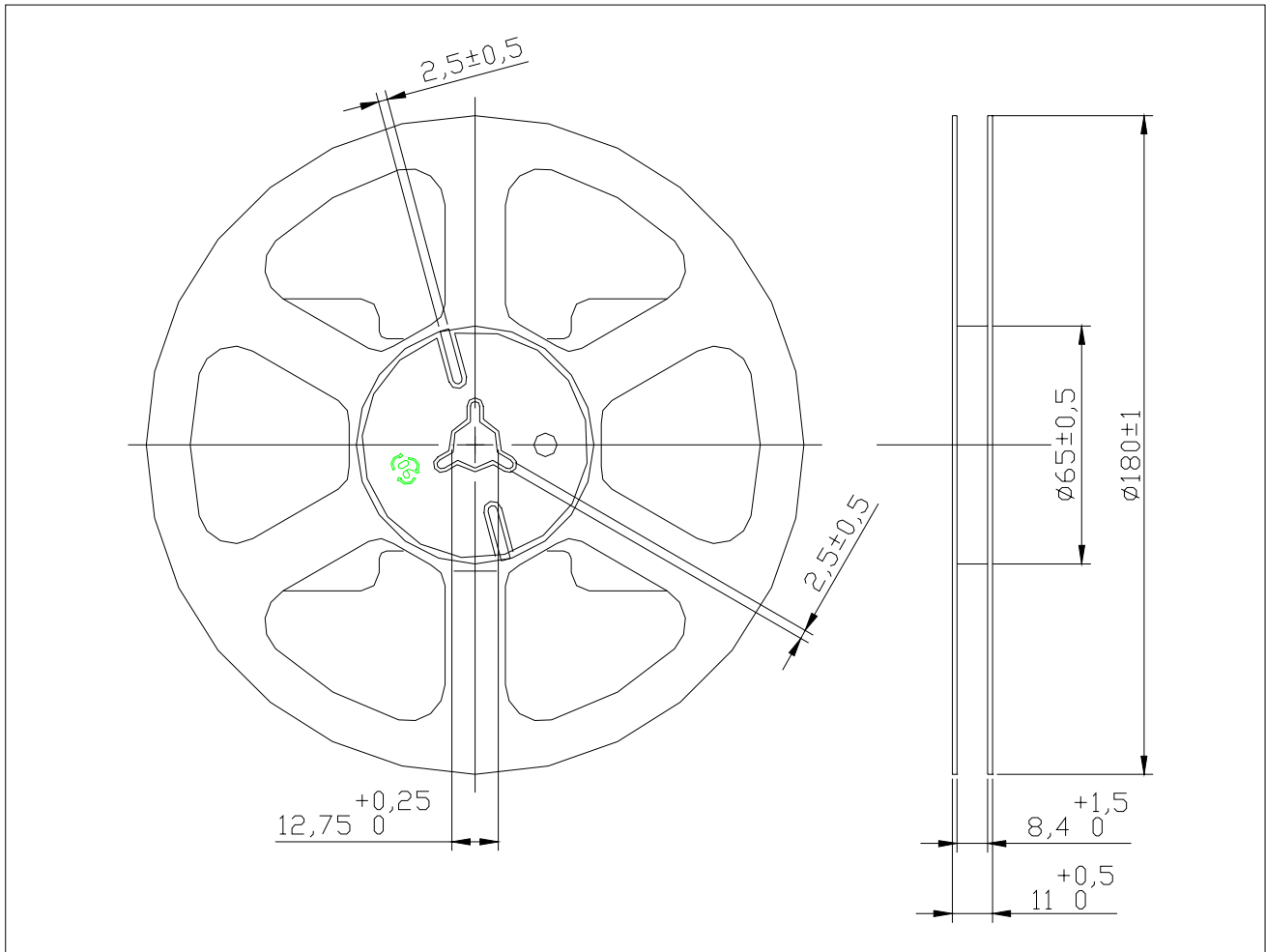
PART NUMBER AND CHARACTERISTICS TABLE BCCB -1005E1 SERIES

Part No.	Impedance(Ω) +/- 25%	Test Freq.(MHz)	DCR(Ω) (Max.)	Rated Current (mA)
BCCB-1005E1-300T	30	100	0.30	500
BCCB-1005E1-400T	40	100	0.30	300
BCCB-1005E1-600T	60	100	0.40	200
BCCB-1005E1-800T	80	100	0.30	500
BCCB-1005E1-121T	120	100	0.50	200
BCCB-1005E1-241T	240	100	0.80	100
BCCB-1005E1-301T	300	100	0.80	100
BCCB-1005E1-601T	600	100	1.00	100

Specification For Approval

REEL DIMENSIONS

Unit: mm

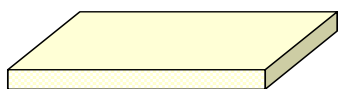
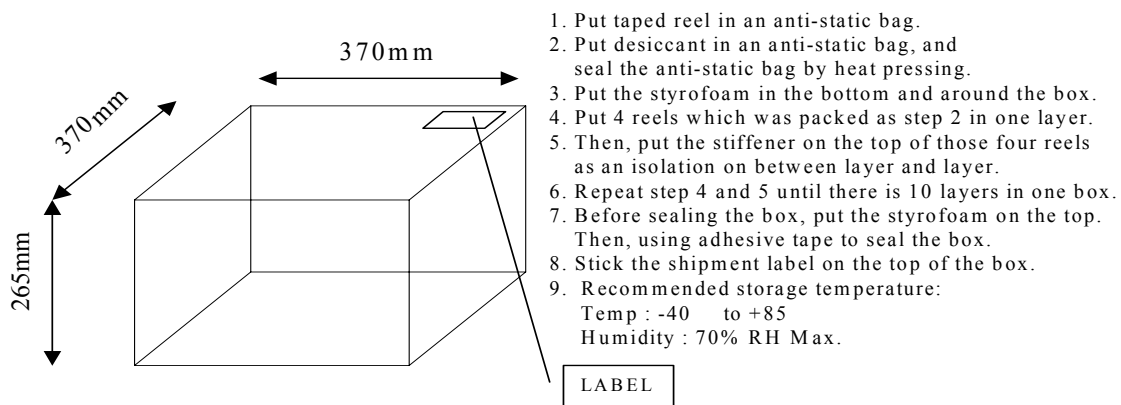


Reel Packaging Quantity									
PART SIZE		1005	1608	201209	201212	3216	3225	4516	4532
7" REEL	Qty. (pcs)	10,000	4,000	4,000	3,000	3,000	2,000	2,000	1,000
13" REEL		NA	NA	10,000	10,000	10,000	5,000	5,000	2,500
BULK		20,000	20,000	20,000	20,000	20,000	10,000	10,000	10,000

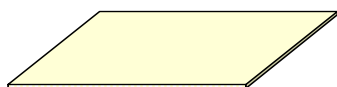
Specification For Approval

PACKING

Carton size	L*W*H (mm)	Loading Quantity 7" (reels)	Loading quantity 13" (reels)
L	370*370*265	40	12
M	370*370*133	20	5
S	370*200*133	20	-



Styrofoam: x 6 (350mm*350mm*15mm)



Stiffener: x 10 (340*340mm)



Taped reel + desiccant + anti-static bag: x 40

Specification For Approval

Leaching	The chip should not crack ; More than 90% of the terminal electrode should be covered with solder , free from defects, chip body should not exposed.	1.Solder: Alpha Sn100 2.Solder Temp: 260 ±5 3.Flux: Rosin 4.Dip time: 10 ±1 sec
Solderability 1 (IR Re-flow test)	1.Sn cover area need to over half thickness of chip 2.Chip shift distance under 50% of width 3.No short , open ,...etc defect symptom	1.Solder: M705-GRN360-K2-V Sn96.5/Ag3/Cu0.5 2.General:135/135/195/235 3.100% TIN:155/155/220/265
Solderability 2	More than 90% of the terminal electrode should be covered with new solder	1.Solder: Alpha Sn100 2.Solder Temp.:230 ±5 3.Flux: Rosin 4.Dip time: 4±1 sec
Terminal Strength	The terminal electrode should not break off nor the ferrite damaged	100505>0.2kgt , 160808>0.3kgt , 201209>0.6kgt , 201212>0.6kgt , 321611>1.0kgt , 322513>1.0kgt , 451616>1.0kgt , 453215>1.5kgt , BCCBA3216>1.2kgt ; pulling time:30 ±5 sec
Bending Strength	The ferrite should not be damaged by force applied on the right	100505>0.2kgf , 160808>0.3kgf , 201209>1.0kgf , 201212>1.0kgf , 321611>2.0kgf , 322513>2.5kgf , 451616>2.5kgf , 453215>2.5kgf , BCCBA3216>2.0kgf
Flexure Strength	No mechanical damage shall be noticed even when the board is bent 2 mm (0.079 inches)	1.At ambient temperature & Humidity 2.To bend 2 mm
Thermal Shock	1.No mechanical damage 2.Inductance should be within ±5% of the initial value 3.Q value should be within ±30% of the initial value 4.Impedance value should be	1.Temperature:-40 ~ 85 For 30 minutes each 2.Cycle: 100 cycles 3.Measurement: At ambient temperature 24 hours After test completion

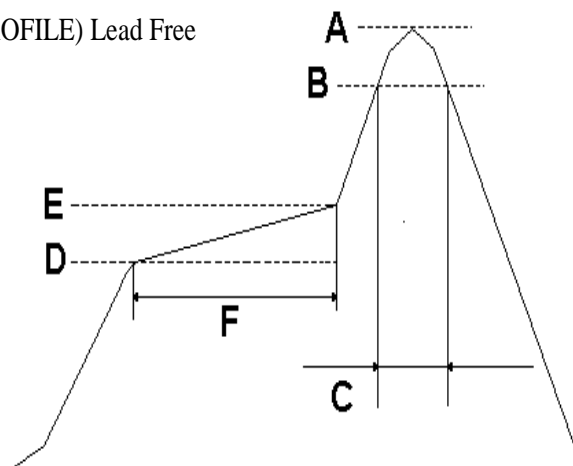
Specification For Approval

	within $\pm 20\%$ of the initial value	
Temperature Cycling	<ol style="list-style-type: none"> 1.No mechanical damage 2.Inductance should be within $\pm 5\%$ of the initial value 3.Q value should be within $\pm 30\%$ of the initial value 4.Impedance value should be within $\pm 20\%$ of the initial value 	<ol style="list-style-type: none"> 1. Temperature: $-40 \sim 125$ 2. Cycle: 100 cycles 3. Measurement: At ambient temperature 24 hours After test completion
Biased Humidity	<ol style="list-style-type: none"> 1.No mechanical damage 2.Inductance should be within $\pm 5\%$ of the initial value 3.Q value should be within $\pm 30\%$ of the initial value 4.Impedance value should be within $\pm 20\%$ of the initial value 	<ol style="list-style-type: none"> 1. Temperature: 40 2. Humidity: 85 % RH 3. Applied current: Full rated current 4. Testing time: 1000 hrs 5. Measurement: At ambient temperature 24 hours After test completion
Rated Current	<ol style="list-style-type: none"> 1. BCCB / BCCL / BCCLH product Surface temperature below room temperature plus 10 2. High current DC power (ES) product surface temp. below room temperature plus 40 	<ol style="list-style-type: none"> 1. At ambient temperature & humidity 2. Testing time: 5 minutes (under full rated current)

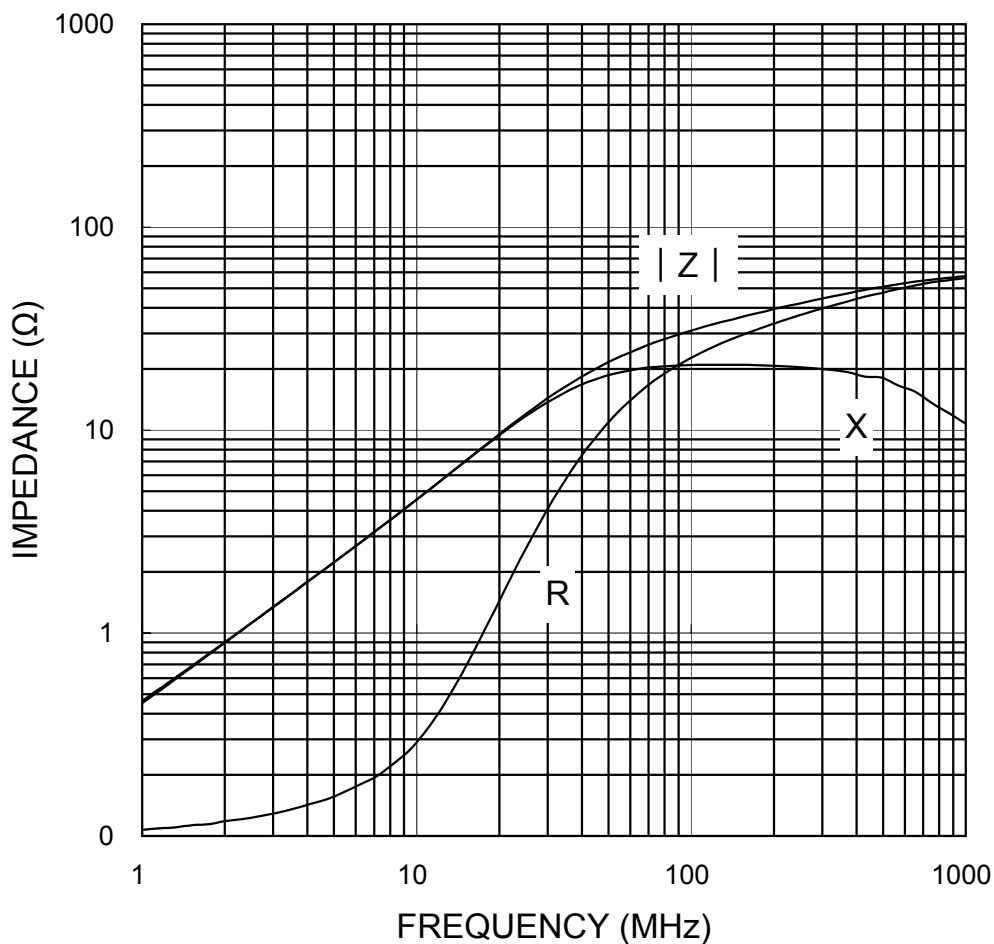
Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

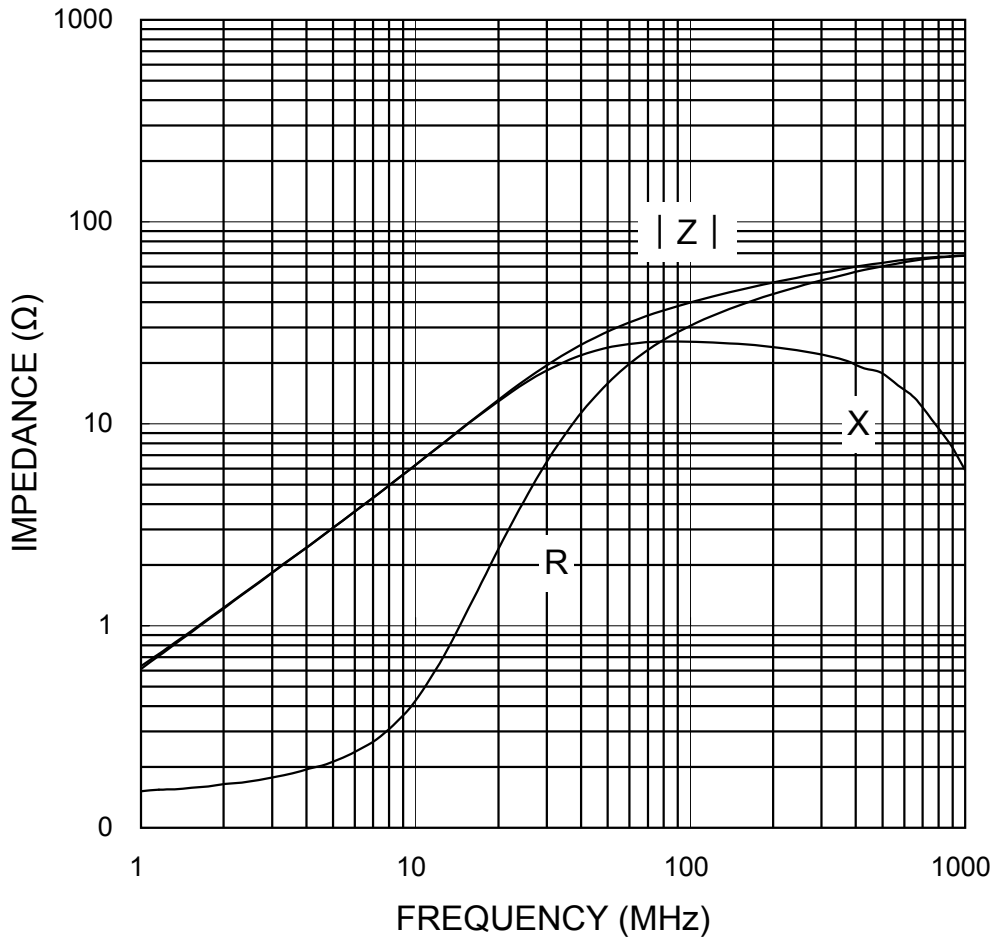
A	260 ± 5
B	230 ± 5
C	$30 \pm 10 \text{sec}$
D	150
E	180
F	$90 \pm 30 \text{sec}$



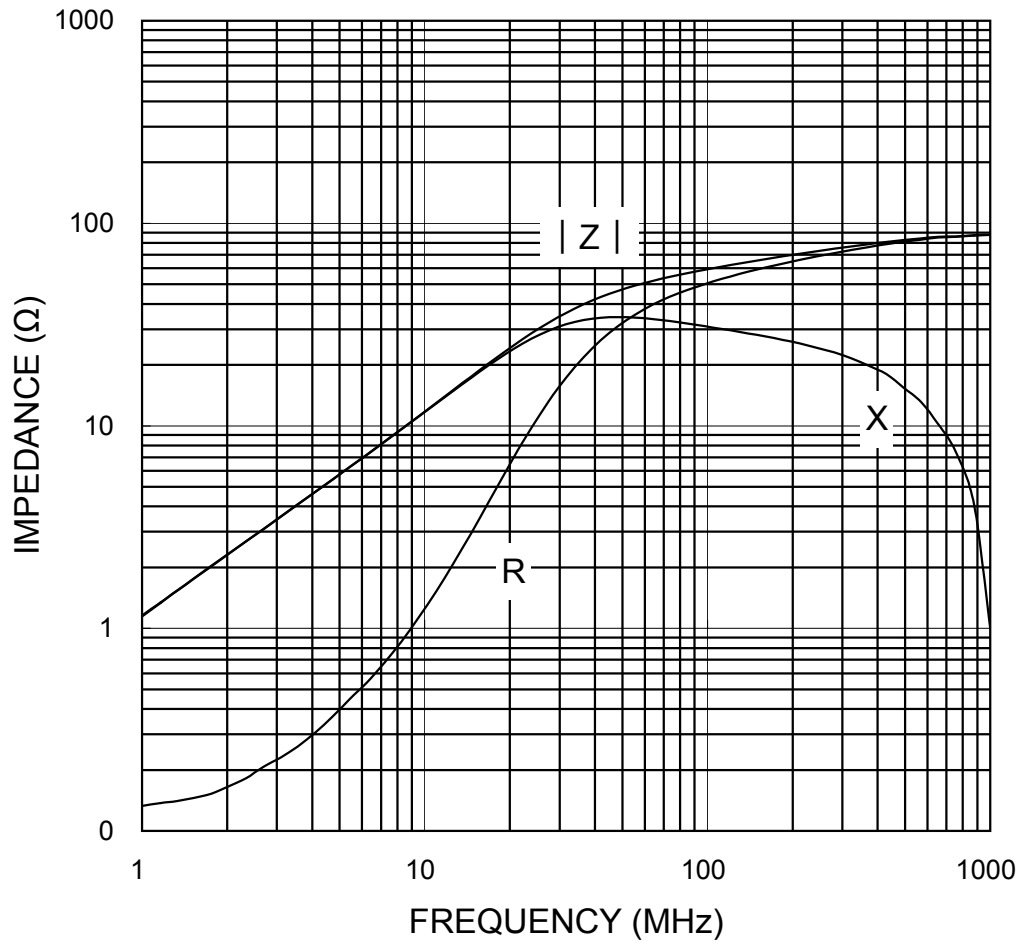
BCCB-1005E1-300T



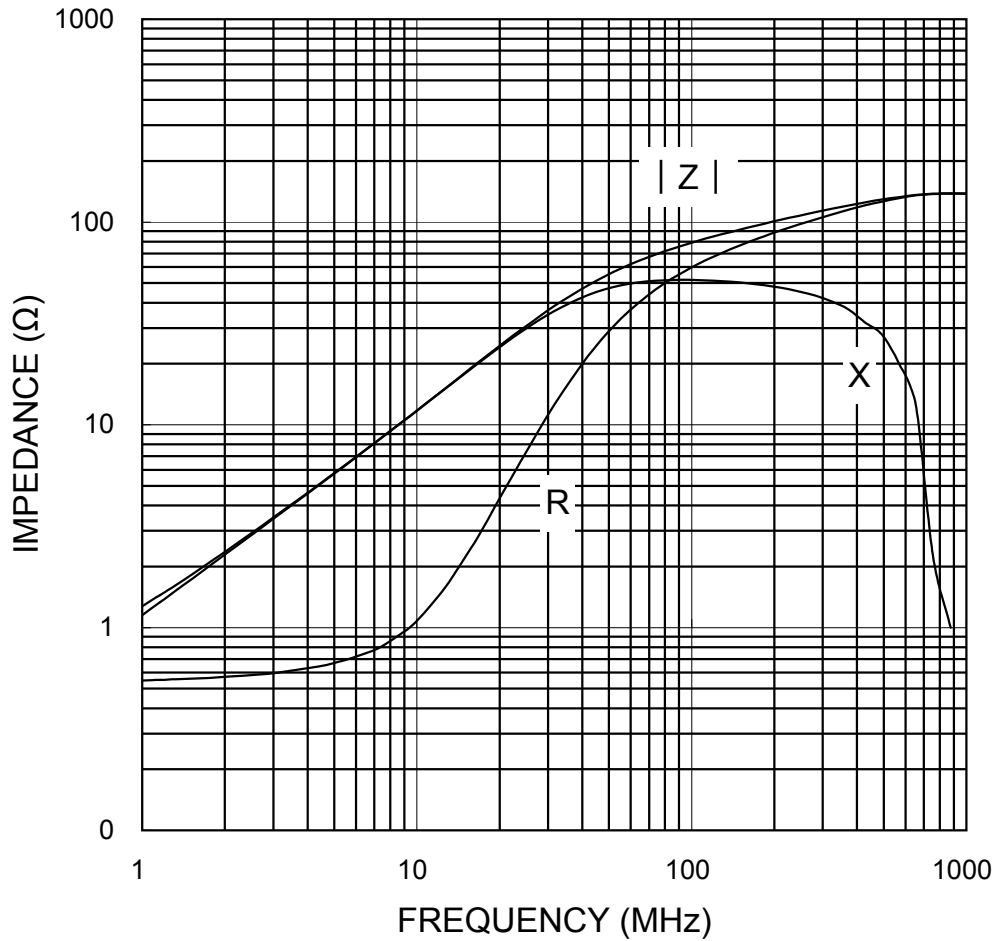
BCCB-1005E1-400T



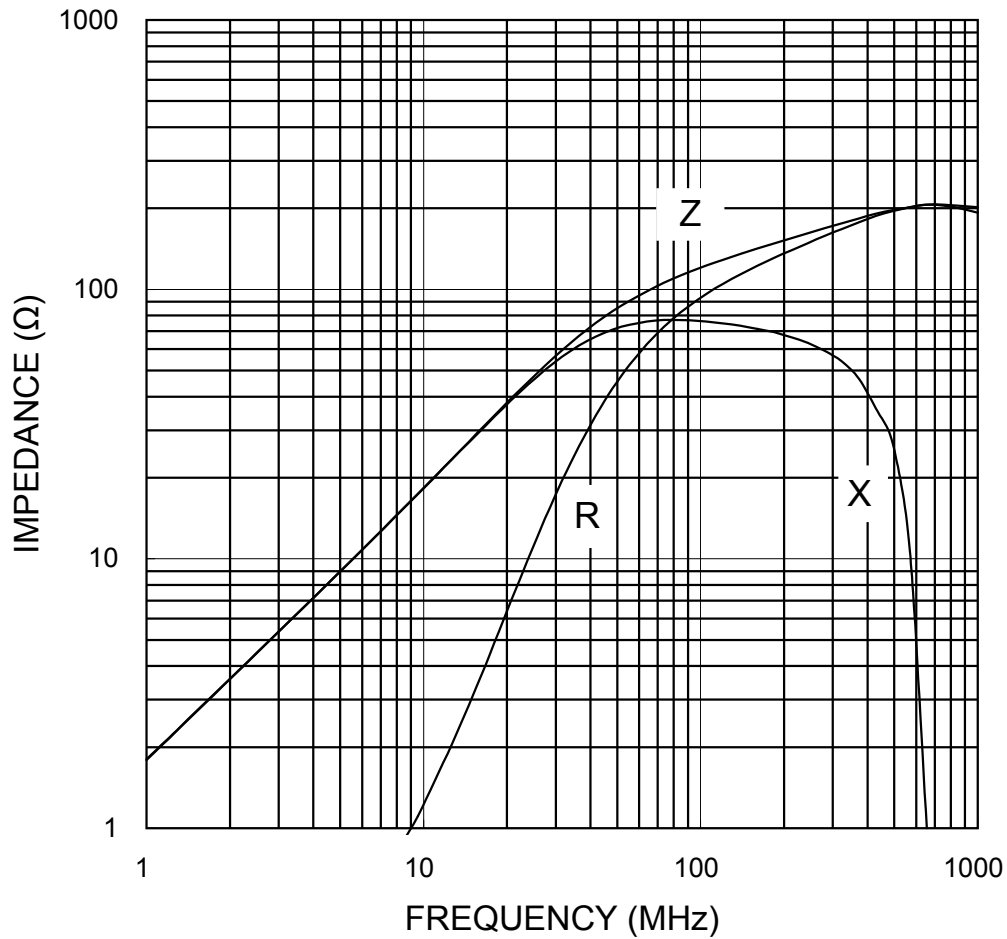
BCCB-1005E1-600T



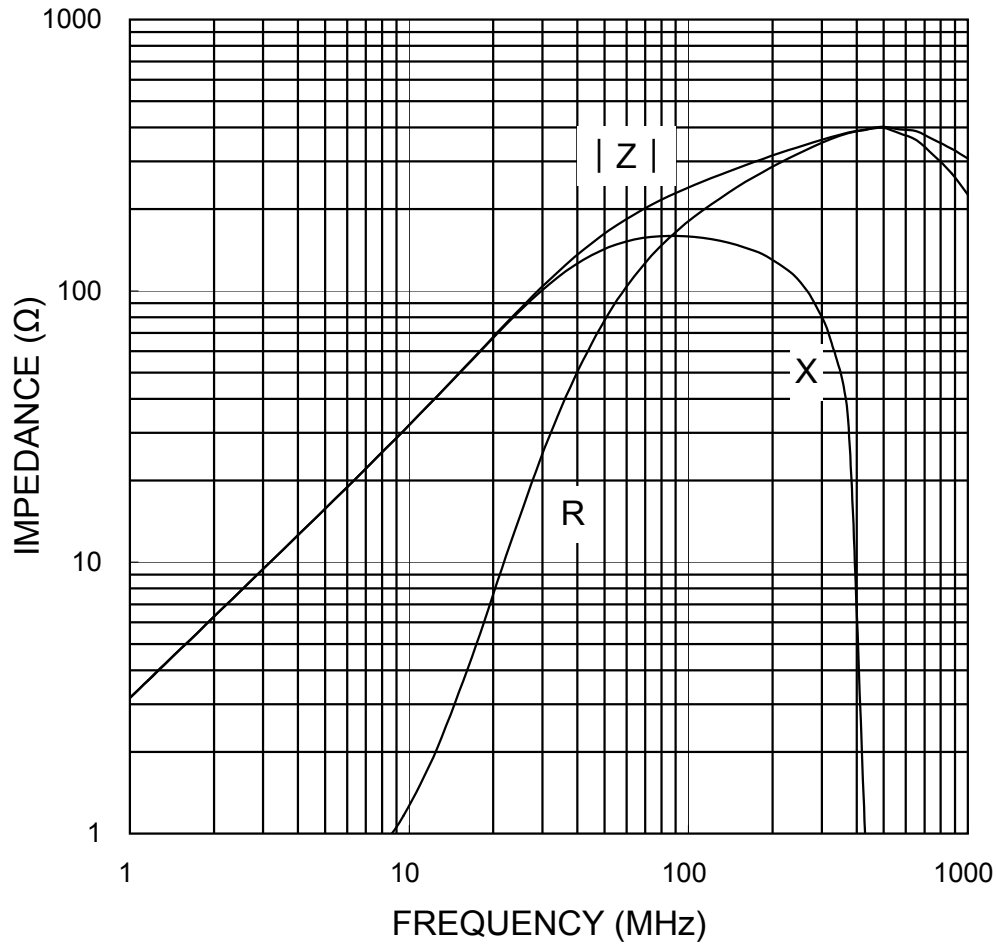
BCCB-1005E1-800T



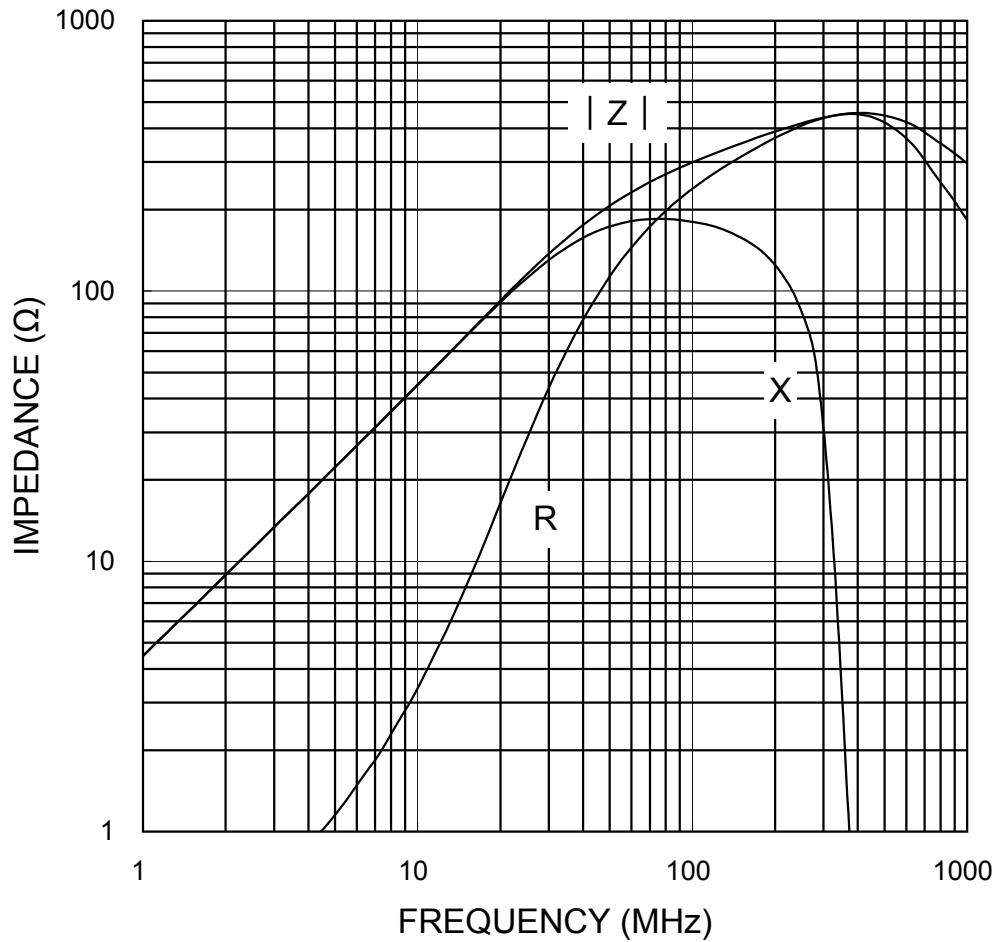
BCCB-1005E1-121T



BCCB-1005E1-241T



BCCB-1005E1-301T



BCCB-1005E1-601T

